

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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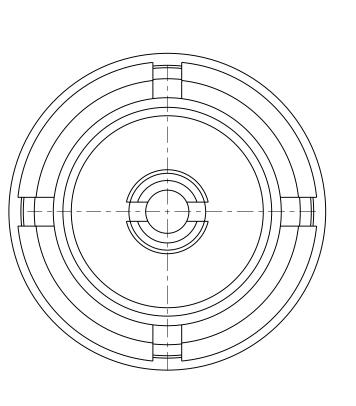






SMP-FSBA-645 REVISIONS DRAWING NO. REV DESCRIPTION DATE ECO APPR THIRD ANGLE PROJ. \oplus \lhd A RELEASE TO MFG 2/25/05 45416

SCALE 6.000



I. MATERIALS AND FINISHES:
BODY - BeCu, GOLD PLATING, .000030 [0.8] THICK OVER NICKEL

A. IMPEDANCE: 50 OHM
B. FREQUENCY RANGE: DC - 26.5 GHz
C. VSWR(RETURN LOSS): 1.2 (20.8 dB), MAX. DC-10GHz
| 1.4 (15.6 dB), MAX. 10-18GHz
| 1.5 (14 dB), MAX. 18-26.5GHz
| D. DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS, MIN.

DURABILTIY: 100 CYCLES MIN.
ENGAGEMENT FORCE: 15 LB [67 N] MAX
DISINGAGEMENT FORCE: 2 LB [9 N] MIN
TEMERATURE RANGE: -65° C TO 165° C

A. QUANTITY: SINGLE PACK
B. MARKING: AMPHENOL, SMP-FSBA-645, DATE CODE

CONTACT - BeCu, GOLD PLATING, .000030 [0.8] THICK OVER NICKEL

{NOTES:

2. ELECTRICAL:

3. PHYSICAL:

4. PACKAGING:

INSULATOR - PTFE

.254 REF — [6,45] Ø.132 REF [3,35] INTERFACE PER-MIL-STD-348 SERIES SMP (BOTH SIDES) .039+.010 [0,99+0,25] REQUIRED JACK TO JACK SPACING FOR BLIND MATE APPLICATIONS

> CUSTOMER OUTLINE DRAWING ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES AND TOLERANCES ARE: 2 PLACE DECIMAL 3 PLACE DECIMAL ANGLES ±.015 (0,381 mm) ±.005 (0,127 mm) ± 1°	MATERIAL	DRAWN MIKE HOYACK	DATE 10-Dec-02	ASSEMBLY	Amphenol RF Danbury, CT, USA
NOTICE - These drawings, specifications, or other data (I) are, and remain the property of Amphenol Corp. (2) must be returned upon request; and (3) are confidential and not to be disclosed to any person other than those to whom they	REFERENCE GEN# ASSYF4_SMP EAR# 796, PREVIOUSLY 322 &1693	ENGINEER MIKE HOYACK	DATE 10-Dec-02	FEMALE TO FEMALE	Tainan, Taiwan Shenzhen, China
are given by Amphenol Corp. The furnishing of these drawings, specifications, or other data by Amphenol Corp., or to any other person to anyone for any purpose is not to be regarded by implication or otherwise in any manner licensing, granting rights or permitting such holder or any other person to manufacture, use or sell any product, process or design, patented or otherwise, that may in any way be related to or disclosed by said drawings, specifications, or other data.		APPROVED OWEN BARTHELMES	DATE 2/23/05		www.amphenolrf.com SCALE: 25.0:1 SHEET 2 OF 2
		CAD FILE I:\SMP\SMP-FSBA-645		code id dwg sizedrawing no 74868 B SI	MP-FSBA-645 REV